RELIABILITY REPORT

FOR

MAX4352EUK+
(MAX4452/MAX4352, MAX4453/MAX4353, MAX4454/MAX4354)

PLASTIC ENCAPSULATED DEVICES

December 23, 2008

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
Ken Wendel
Quality Assurance
Director, Reliability Engineering

Conclusion

The MAX4352EUK+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

Table of Contents

I. Device Description

A. General

The MAX4452/MAX4352 single, MAX4453/MAX4353 dual, and MAX4454/MAX4354 quad amplifiers combine high-speed performance with ultra-low power consumption. The MAX4452/MAX4453/MAX4454 are unity-gain stable and achieve a -3dB bandwidth of 200MHz, while the MAX4352/MAX4353/MAX4354 are compensated for a minimum closed-loop gain of +5V/V and achieve a 80MHz -3dB bandwidth. These devices consume only 620µA of supply current per amplifier. These amplifiers operate from a +2.7V to +5.25V single supply and feature rail-to-rail outputs. Along with an excellent speed/power ratio of 323MHz/mA, these devices feature a slew rate of 95V/µs and fast 20ns rise and fall times. These devices are ideal for low-power/low-voltage systems that require wide bandwidth such as cell phones and keyless entry systems. The MAX4452/MAX4352 are available in miniature 5-pin SC70 and SOT23 packages, while the MAX4453/MAX4353 are available in tiny 8-pin SOT23, thin SOT23, and SO packages. The MAX4454/MAX4354 are available in space-saving 14-pin TSSOP and SO packages.

II. Manufacturing Information

A. Description/Function:	Low-Cost, +3V/+5V, 620µA, 200MHz, Single-Supply Op Amps with Rail-to-Rail Outputs
B. Process:	CB3
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Carsem Malaysia, ISPL Philippines, Hana Thailand, UTL Thailand, Unisem Malaysia
F. Date of Initial Production:	January 27, 2001

III. Packaging Information

A. Package Type:	5-pin SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-2501-0050
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	324.3°C/W
K. Single Layer Theta Jc:	82°C/W

IV. Die Information

A. Dimensions:	30 X 30 mils
B. Passivation:	Si_3N_4 (Silicon nitride)
C. Interconnect:	Gold
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal1 = 0.5 / Metal2 = 0.6 / Metal3 = 0.6 microns (as drawn)
F. Minimum Metal Spacing:	Metal1 = 0.45 / Metal2 = 0.5 / Metal3 = 0.6 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 150°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 72 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 14.9 \times 10^{-9}$

$\lambda = 14.9$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at http://www.maxim-ic.com/. Current monitor data for the CB3 Process results in a FIT Rate of 0.14 @ 25C and 2.42 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The OX15-1 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1
Reliability Evaluation Test Results

MAX4352EUK+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 150°C Biased Time = 192 hrs.	DC Parameters & functionality	72	0
Moisture Testing (Note 2)				
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data